

**IN THE CLAIMS:**

Claims 2, 3 and 10 have been amended herein. All of the pending claims 1 through 15 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

**Listing of Claims:**

1. (Previously Presented) A semiconductor die assembly comprising:  
a semiconductor substrate having a first surface and a second surface, the semiconductor substrate including at least one opening extending therethrough between the semiconductor substrate first surface and the semiconductor substrate second surface;  
at least one semiconductor die having an active surface with at least one electrical connection area disposed on the semiconductor die active surface, the at least one semiconductor die oriented having the at least one electrical connection area substantially aligned with the at least one semiconductor substrate opening; and  
at least one piece of adhesive tape interposed between and attaching the semiconductor die active surface and the semiconductor substrate first surface, a width of the at least one piece of adhesive tape extending beyond at least one of an edge of the at least one semiconductor substrate opening and an edge of the at least one semiconductor die to provide a detectable surface of the at least one piece of adhesive tape.

2. (Currently Amended) A semiconductor die assembly comprising:
- a semiconductor substrate having a first surface and a second surface, wherein the semiconductor substrate includes at least one opening defined therethrough between the semiconductor substrate first surface and the semiconductor substrate second surface;
  - at least one semiconductor die having an active surface with at least one electrical connection area disposed on the semiconductor die active surface, the at least one semiconductor die oriented having the at least one electrical connection area substantially aligned with the at least one semiconductor substrate opening, the electrical connection area disposed on the semiconductor die active surface, the at least one electrical connection area directly connected to at least one output electrical connection of the at least one semiconductor ~~device;~~ die; and
  - at least one adhesive tape interposed between and attaching the semiconductor die active surface and the semiconductor substrate first surface, a width of the at least one adhesive tape extending at least proximate an edge of the at least one semiconductor die to an edge of the at least one semiconductor substrate opening, the width of the at least one adhesive tape extends beyond the edge of the at least one semiconductor substrate opening a distance into the at least one semiconductor substrate opening to provide a detectable surface within the at least one semiconductor substrate opening.

3. (Currently Amended) A semiconductor die assembly comprising:  
a semiconductor substrate having a first surface and a second surface, wherein the semiconductor substrate includes at least one opening defined therethrough between the semiconductor substrate first surface and the semiconductor substrate second surface;  
at least one semiconductor die having an active surface with at least one electrical connection area disposed on the semiconductor die active surface, the at least one semiconductor die oriented having the at least one electrical connection area substantially aligned with the at least one semiconductor substrate opening, the at least one electrical connection area disposed on the semiconductor die active surface, the at least one electrical connection area directly connected to at least one output electrical connection of the at least one semiconductor device; die; and  
at least one adhesive tape interposed between and attaching the semiconductor die active surface and the semiconductor substrate first surface, a width of the at least one adhesive tape extending at least proximate an edge of the at least one semiconductor die to an edge of the at least one semiconductor substrate opening and extending beyond the edge of the at least one semiconductor die a distance on the semiconductor substrate first surface to provide a detectable adhesive tape surface on the semiconductor substrate first surface.
4. (Previously Presented) The semiconductor die assembly of claim 1, further including at least one electrical connection extending between the at least one electrical connection area and at least one trace on the semiconductor substrate second surface.
5. (Previously Presented) The semiconductor die assembly of claim 4, wherein the at least one electrical connection comprises a bond wire.
6. (Previously Presented) The semiconductor die assembly of claim 4, wherein the at least one electrical connection comprises a TAB connection.

7. (Previously Presented) The semiconductor die assembly of claim 4, further including a glob top material disposed within the at least one semiconductor substrate opening encasing the at least one electrical connection.

8. (Previously Presented) The semiconductor die assembly of claim 7, further including an encapsulant material encasing the at least one semiconductor die and the glob top material.

9. (Previously Presented) The semiconductor die assembly of claim 1, wherein the at least one adhesive tape comprises a planar carrier film including a first surface having a first adhesive disposed thereon and a second surface having a second adhesive disposed thereon.

10. (Currently Amended) A semiconductor die assembly comprising:  
a semiconductor substrate having a first surface and a second surface, wherein the semiconductor substrate includes at least one opening defined therethrough between the semiconductor substrate first surface and the semiconductor substrate second surface;  
at least one semiconductor die having an active surface with at least one electrical connection area disposed on the semiconductor die active surface, the at least one semiconductor die oriented having the at least one electrical connection area substantially aligned with the at least one semiconductor substrate opening; and  
at least one adhesive tape interposed between and attaching the semiconductor die active surface and the semiconductor substrate first surface, a width of the at least one adhesive tape extends at least proximate an edge of the at least one semiconductor die to an edge of the at least one semiconductor substrate opening, the at least one adhesive tape comprises a planar carrier film including a first surface having a first adhesive disposed thereon and a second surface having a second adhesive disposed thereon, and the composition of the first adhesive differs from a composition of the second adhesive for substantially preventing damage to a portion of the active surface of the semiconductor die by filler

particles in a material used to fill the at least one opening in the semiconductor substrate being located between the first surface of the semiconductor substrate and the active surface of the at least one semiconductor die.

11. (Previously Presented) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate the at least one adhesive tape and the edge of the at least one semiconductor die.

12. (Previously Presented) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate the at least one adhesive tape and the edge of the at least one semiconductor substrate opening.

13. (Previously Presented) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate the at least one adhesive tape and the active surface of the at least one semiconductor die.

14. (Previously Presented) The semiconductor die assembly of claim 1, further comprising at least one fillet located proximate the at least one adhesive tape and the semiconductor substrate first surface.

15. (Previously Presented) A computer comprising:
- at least one semiconductor die assembly, the semiconductor die assembly comprising:
    - a semiconductor substrate having a first surface and a second surface, wherein the semiconductor substrate includes at least one opening defined therethrough between the semiconductor substrate first surface and the semiconductor substrate second surface;
  - at least one semiconductor die having an active surface with at least one electrical connection area disposed on the semiconductor die active surface, the at least one semiconductor die oriented having the at least one electrical connection area substantially aligned with the at least one semiconductor substrate opening; and
  - at least one piece of adhesive tape interposed between and attaching the semiconductor die active surface and the semiconductor substrate first surface, a width of the at least one piece of adhesive tape extending beyond at least one of an edge of the at least one semiconductor substrate opening and an edge of the at least one semiconductor die to provide a detectable surface of the at least one piece of adhesive tape.